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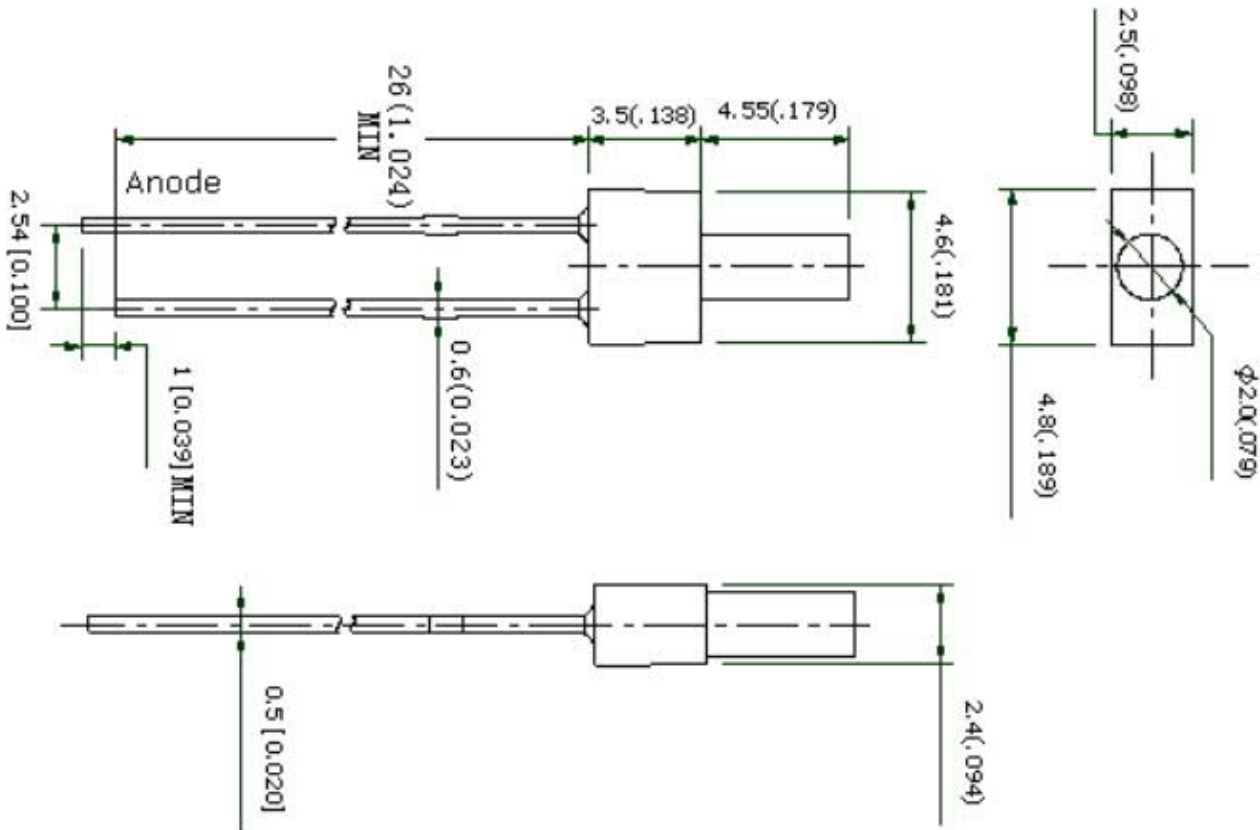
Data Sheet

REVISION	01
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APPROVAL BY	JASON
PREPARED BY	LUOFAXING

Features:

1. Low power consumption
2. High efficiency
3. Reliable and rugged
4. Chip Material: GaP
5. Lens Color: Green Diffused
6. Source Color: Yellowish GREEN

Outline Dimensions:



Note :

1. All dimensions are in millimeters (inches)
2. Tolerance is $\pm 0.25\text{mm}$ (0.01”) unless otherwise noted
3. Specifications are subject to change without notices.

Absolute Maximum Ratings at Ta=25°C :

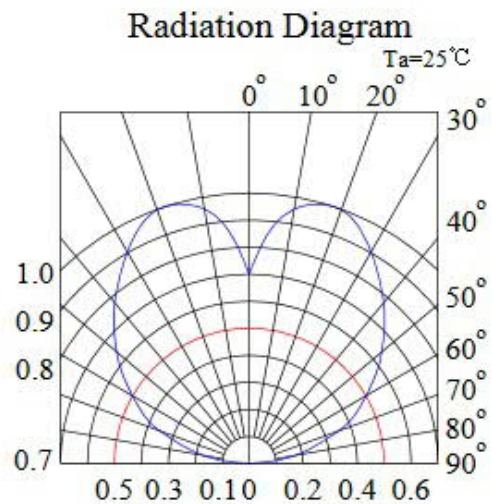
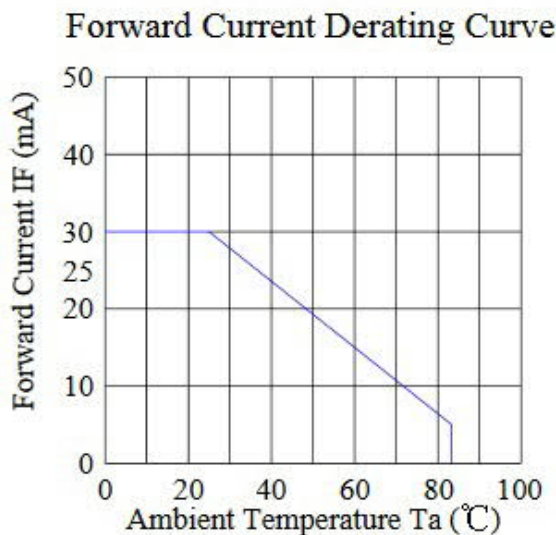
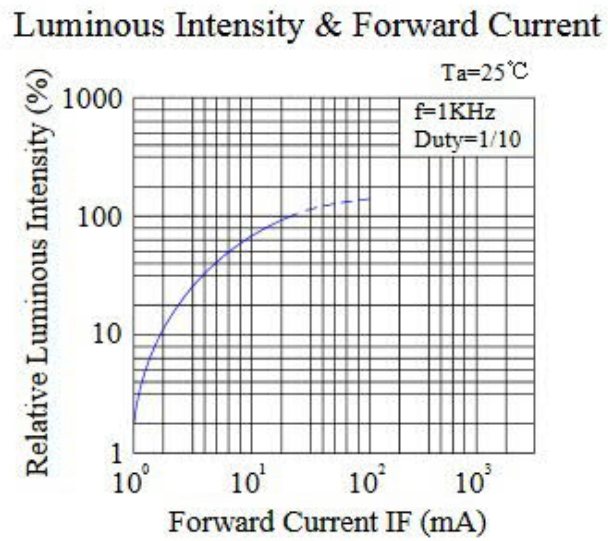
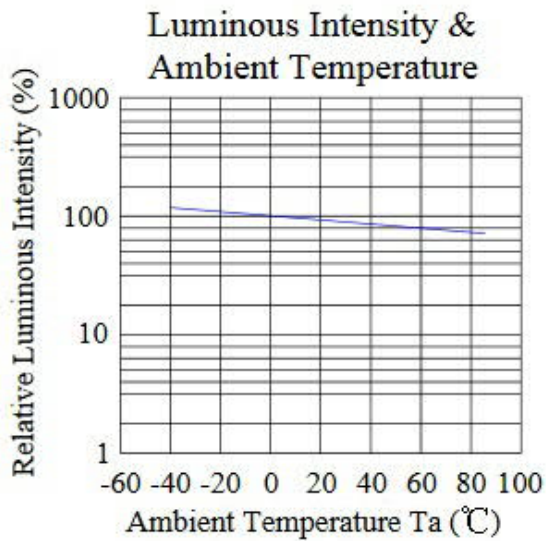
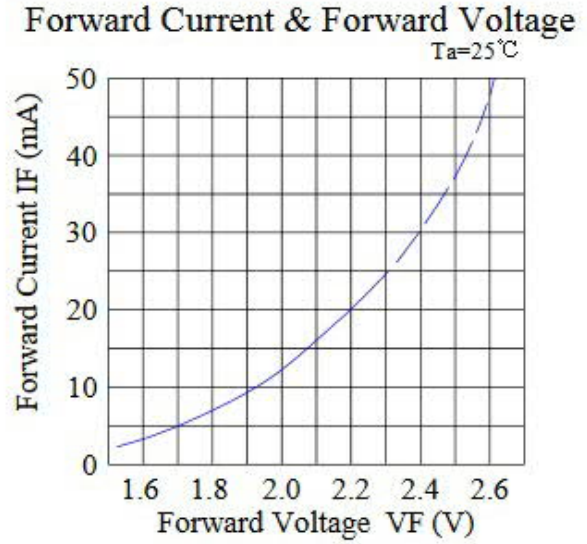
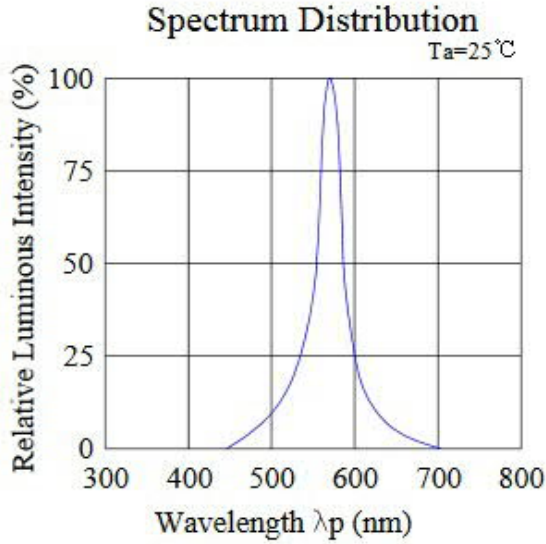
Parameter	Maximum	Unit
Power Dissipation	78	mW
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)	100	mA
Continuous Forward Current	30	mA
Derating Linear From 50°C	0.3	mA/°C
Reverse Voltage	5	V
Operating Temperature Range	-20°C to +80°C	
Storage Temperature Range	-30°C to +85°C	
Lead Soldering Temperature [1.6mm(0.63") from body]	260°C for 3 Seconds	

Electrical/Optical Characteristics at Ta=25°C :

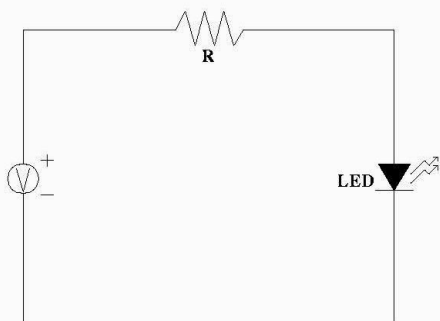
Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Luminous Intensity	I _v	I _F =20mA	3	7		mcd
Dominant Wavelength	λ _d	I _F =20mA		570		nm
Viewing Angle	2θ 1/2	I _F =20mA		120		deg
Forward Voltage	V _F	I _F =20mA	1.6	2.2	2.6	V
Reverse Current	I _R	V _R =5V			10	uA

Typical Electrical/Optical Characteristics Curve:

(25°C Ambient Temperature Unless Otherwise Noted)



● Test Circuit



Reliability Test Standard

NO	Test Item	Test state	Test Conditions	Test Hours/Cycle	Sample /Size	Ac/Re
1	Solder Heat	Motionless state	TEMP:260°C±5°C	10SEC	40PCS	0/1
2	DC Operating Life	Development	TEMP:23±5°C IF=20mA	1000HRS	40PCS	0/1
3	High Temperature Storage	Motionless state	TEMP:105°C	1000HRS	40PCS	0/1
4	Low Temperature Storage	Motionless state	TEMP:-45°C	1000HRS	40PCS	0/1
5	High Temperature High Humidity	Development	Ta= 65±5°C RH= 90 ~ 95%	240H±2H	40PCS	0/1
6	Temperature Cycle	Development	H:+65°C 95% 1H┆10MIN L:-25°C 1H	40CYCLES	40PCS	0/1
7	Thermal Shock	Motionless state	H:+105°C 30min ┆3MIN L:-45°C 30min	20CYCLES	40PCS	0/1